

Features

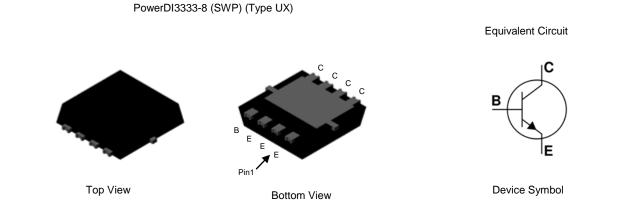
- BV_{CEO} > 25V
- Small Form Factor Thermally Efficient Package.
 Enables Higher Density End Products
- $I_C = 3A$ High Continuous Current
- I_{CM} = 8A Peak Pulse Current
- Low Saturation Voltage $V_{CE(SAT)}$ < 200mV @ 1A
- Complementary PNP Type: DXTP07025BFG
- Rated to +175°C Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Solderable per MIL-STD-202, Method 208 ⁽²³⁾
- Weight: 0.03 grams (Approximate)

Applications

- Load Switch
- Linear Regulator



Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DXTN07025DBFG-7	2H2	7	12	2,000
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.				

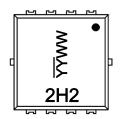
No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

PowerDI3333-8 (SWP) (Type UX)



2H2= Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated. DXTN07025BFG

Document Number DS41041 Rev.2 - 2



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	35	V
Collector-Emitter Voltage	V _{CEO}	25	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	Ιc	3	А
Peak Pulse Current	I _{CM}	8	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 5)		0.9	W
Power Dissipation	(Note 6)	PD	2.1	W
	(Note 7)		3.1	W
	(Note 5)		140	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	R _{0JA}	65	°C/W
	(Note 7)		44	°C/W
Thermal Resistance, Junction to Leads (Note 8	R _{θJL}	8.5	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C	

ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	400	V	С
Notes: 5. For a device mounted with the collector tab on MRP FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.				

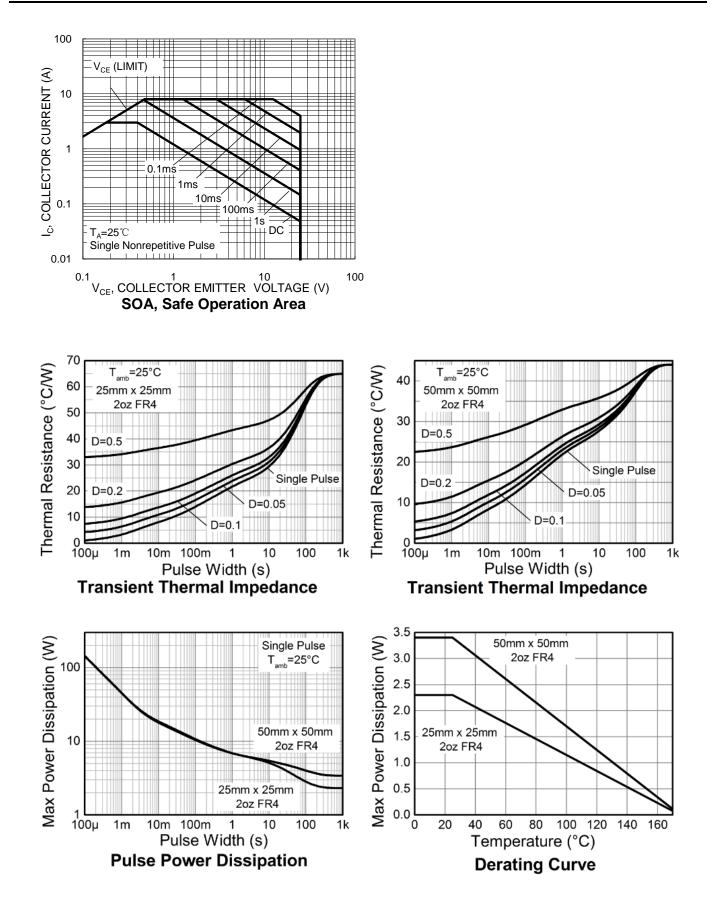
6. Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper.

7. Same as Note 5, except the device is mounted on 50mm x 50mm 2oz copper.

Thermal resistance from junction to solder-point (at the collector tab). Refer to JEDEC specification JESD22-A114 and JESD22-A115. 8. 9.



Thermal Characteristics and Derating Information





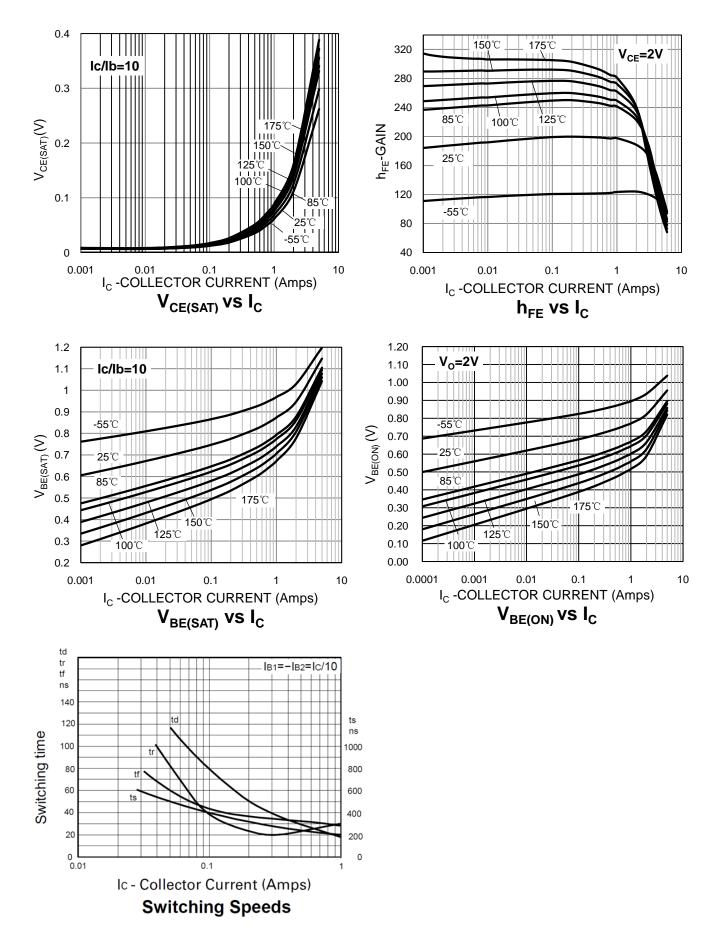
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	35	136		V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV _{CEO}	25	47	—	V	$I_{\rm C} = 10 {\rm mA}$
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.4		V	I _E = 100μA
Collector Cut-Off Current	1	—		20	nA	$V_{CB} = 30V$
Collector Cut-On Current	I _{CBO}	_	_	10	μA	$V_{CB} = 30V, T_A = +125^{\circ}C$
Emitter Cut-Off Current	I _{EBO}	_		20	nA	$V_{EB} = 6V$
Collector-Emitter Saturation Voltage (Note 10)	M	_	69	200	mV	$I_{\rm C} = 1$ A, $I_{\rm B} = 100$ mA
Collector-Enlitter Saturation Voltage (Note 10)	VCE(SAT)	_	180	400	mV	$I_{C} = 3A, I_{B} = 300mA$
Base-Emitter Saturation Voltage (Note 10)	V _{BE(SAT)}	_	0.86	1.1	V	$I_{\rm C} = 1$ A, $I_{\rm B} = 100$ mA
Base-Emitter Turn-On Voltage (Note 10)	V _{BE(ON)}	—	0.78	1	V	$I_C = 1A$, $V_{CE} = 2V$
	h _{FE}	70	198	_	_	$I_C = 50 \text{mA}, V_{CE} = 2 \text{V}$
DC Current Cain (Note 10)		100	191	300	_	$I_C = 1A, V_{CE} = 2V$
DC Current Gain (Note 10)		75	180			$I_{C} = 2A, V_{CE} = 2V$
		15	98			$I_{C} = 6A, V_{CE} = 2V$
Current Gain-Bandwidth Product	f _T	150	240	_	MHz	$V_{CE} = 5V, I_C = 100mA, f = 100MHz$
Switching Timos	t _{ON}	_	55	—	ns	$I_{C} = 500 \text{mA}, V_{CC} = 10 \text{V},$
Switching Times	t _{OFF}	_	300	_	ns	$I_{B1} = -I_{B2} = 50 \text{mA}$
Output Capacitance	COBO	_	25	50	pF	V _{CB} = 10V, f = 1MHz

Note: 10. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



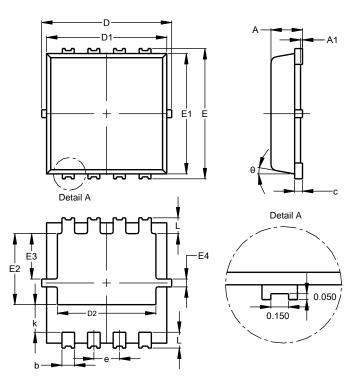
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)





Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



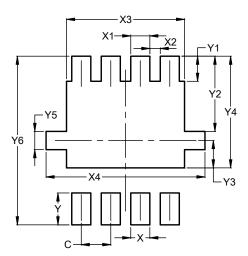
PowerDI3333-8 (SWP) (Type UX)

PowerDI3333-8 (SWP)						
(Type UX)						
Dim	Min	Min Max Ty				
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
c	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Е	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	_	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)	
С	0.650	
Х	0.420	
X1	0.420	
X2	0.230	
X3	2.600	
X4	3.500	
Y	0.700	
Y1	0.550	
Y2	1.650	
Y3	0.600	
Y4	2.450	
Y5	0.400	
Y6	3.700	

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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